

### ABSTRACT OF THE DISCLOSURE

A method 10 for making a multi-layer electronic circuit board 110 having electroplated apertures 18, 20 which may be selectively and electrically isolated from  
5 electrically grounded member 12 and further having selectively formed air bridges and/or crossover members 50 which are structurally supported by material 54, and further having certain exposed connection surfaces 112, selectively and electrically connected to certain  
10 electrically conductive members 34, 42, and 44.